| L     | Тур   | Hits        | Search Text   | DBs  | Time            | Stam  |
|-------|-------|-------------|---|--|-----------------|-------|
| 1     | BRS   | 25          | ("5757126" "5189405" "5731661<br>"5276414" "4633573" "6140150"<br>"5694300" "4016643" "6566596"<br>"6548912" "5771562").pn.                                   | USPAT; US-PGPUB;                                     | <u> </u>        | 04/0  |
| 2     | BRS   | 0           | JP-361102757-\$.did.  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB    | 2004/<br>17:58  | 04/0  |
| 3     | BRS   | 2           | 6664624.pn.   | USPAT; US-PGPUB;<br>EPO: JPO:                        | 2004/<br>18:00  |       |
| 4     | BRS   | 0           | 6664624.URPN.   | USPAT  | 2004/<br>18:05  |       |
| 5     | BRS   | 11          | ("4016643"   "4633573"  <br>"5189405"   "5276414"  <br>"5694300"   "5731661"  <br>"5757126"   "5771562"  <br>"6140150"   "6548912"  <br>"6566596").PN.        | USPAT  | 2004/0          |       |
| 5     | BRS   |             | (semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal near4 protective) and connect\$3  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB    | 2004/0<br>L8:26 | 04/01 |
| ,<br> | BRS   |             | (chip adj resistor) and resin   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB    | 2004/0<br>8:19  | 4/01  |
|       | BRS   | 110         | (semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal) and (front adj (face or surface)) and ((rear or back) adj (face or surface)) | USPAT; US-PGPUB;<br>EPO; JPO:                        | 004/0<br>8:29   | 4/01  |
|       | BRS   | 82 <b>[</b> |   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB    | 004/0<br>8:21   | 4/01  |
| 0     | BRS 6 | j           | ((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal near4 protective) and connect\$3) and ((rear or back) adj (face or surface)) | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB    | 004/04<br>8:27  | 4/01  |
|       | BRS 9 | (<br>(      | semiconductor adj chip) and metal near4 protect\$4)   |  | 004/04<br>3:22  | 1/01  |
|       | BRS 3 | 8 (         | semiconductor adj chip) and I   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB 18 | 004/04<br>3:24  | /01   |

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|----------|------|------|------------|---|---|---------------------|
| 1        | 3 BI | ≀S   | 24         | <pre>(chip adj resistor) and (resinear4 insulating) and electrodes and (semiconductoradj chip) and (metal adj2   (layer or film))</pre>   | HEDATE HE DEDITE                                  | ; 2004/05/16        |
| 14       | 4 BR | .S   | 379        | (semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connects  | USPAT; US-PGPUB<br>EPO; JPO;<br>DERWENT; IBM_TDE  | 2004/04/01          |
| 15       | 5 BR | S,   | 141        | ((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connect\$3) and ((rear or back adj (face or surface))  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDE | 2004/04/01<br>18:27 |
| 16       | BR:  | 5    | 14         | ((semiconductor adj chip) and electrodes and (resin near4 insulating) and (metal adj3 (layer or film)) and connect\$3) and (front adj (face or surface)) and ((rear or back) adj (face or surface)            | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/04/01<br>18:38 |
| 17       | BRS  | 3 4  |            | (("5357056" "5508556"<br>"6314637" "6005474").pn.) and<br>resin   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB | 2004/04/01<br>18:34 |
| 18       | BRS  | 4    |            | (("5357056" "5508556"<br>"6314637" "6005474").pn.) and<br>resin and metal   | USPAT; US-PGPUB;<br>EPO; JPO:                     | 2004/04/01<br>18:35 |
| 19       | BRS  | 2    | ָן<br>בּוֹ | resin and metal adia (lavor or  | USPAT; US-PGPUB.                                  | 2004/04/01          |
| 20       | BRS  | 1!   | 5 s        | ((chip adj resistor) and resin) and (front adj (face or surface)) with connect\$3 with (rear or back) adj (face or surface))  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/04/01          |
| 1        | BRS  | 21   | i(c(c      | (semiconductor adj chip) and electrodes and (resin near4 nsulating) and (metal adj3 layer or film)) and onnect\$3) and (front adj face or surface)) with onnect\$3 with ((rear or back) dj (face or surface)) | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 3004/04/01<br>8:41  |
| 2        | BRS  | 24   | 69 4.      | I   | DERWENT: IBM TOR 1                                | 004/04/01<br>9:05   |
| 3        | BRS  | 93   | 8 43       | 88/108.ccls.  | JSPAT; US-PGPUB; 2                                | 004/04/01<br>9:05   |

|    | Тур   | e Hit  | Search Text  | DBs   | Time Stamp          |
|----|-------|--------|--|---|---------------------|
| 24 | BRS   | 750    | 438/125.ccls.  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/04/01          |
| 25 | BRS   | 702    | 438/126.ccls.  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/04/01<br>19:05 |
| 26 | BRS   | 975    | 438/127.ccls.  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB | 2004/04/01<br>19:05 |
| 27 | BRS   | 13     | (chip adj resistor) and (resing near4 insulating) same electrodes and (semiconductor adj chip) and (metal adj2 (layer or film))                  | HISDAT. HE DONIE                                  | 2004/05/16<br>19:08 |
| 28 | BRS   | 27     | (chip adj resistor) and (resing near4 insulating) same electrodes and (metal adj2 (layer or film))   | HISPATT HIS DOUBTER                               | 2004/05/16<br>18:36 |
| 29 | BRS   | 495    | <pre>(resin near4 insulating) same electrodes and (metal adj2 (layer or film))</pre>   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB | 2004/05/16<br>18:35 |
| 30 | BRS   | 197    | <pre>(resin near4 insulating) same pads and (metal adj2 (layer or film))</pre>   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB | 2004/05/16<br>18:35 |
| 31 | BRS   | 21     | (chip adj resistor) and (resin<br>near4 insulating) same<br>electrodes and (metal adj2<br>(layer or film)) and (via or<br>hole)                  | USPAT; US-PGPUB;                                  | 2004/05/16<br>18:46 |
| 32 | BRS   |        | (resin near4 insulating) same electrodes and (metal adj2 (layer or film)) and (via or hole)  |   | 2004/05/16<br>18:35 |
| 33 | BRS   |        | (resin near4 insulating) same<br>pads and (metal adj2 (layer or<br>film)) and (via or hole)  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB | 2004/05/16<br>L8:35 |
| 4  | BRS   | 8      | (chip adj resistor) and (resin near4 insulating) same electrodes and (semiconductor adj chip) and (metal adj2 (layer or film)) and (via or nole) | USPAT; US-PGPUB;<br>EPO; JPO:                     | 2004/05/16<br>8:36  |
| 5  | BRS : | 11   ā | and (semiconductor adj chip)   |   | 004/05/16<br>8:37   |
| 6  | BRS ] | .2 r   | ind (metal adi2 (laver or  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 004/05/16<br>8:38   |

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|      | Туре                                  | Hits       | Search Text  | DBs   | Time Stam           |
|------|---------------------------------------|------------|--|---|---------------------|
| 37   | BRS                                   | 0          | ("4016643"   "4633573"   "5189405"   "5276414"   "5694300"   "5731661"   "5757126"   "6548912"   "6566596").PN. and (chip adjresistor) | USPAT   | 2004/05/16          |
| 38   | BRS                                   | 93         | (chip adj resistor) and electrodes and (metal adj2 (layer or film)) and (via or hole)  | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/05/16<br>18:47 |
| 39   | BRS                                   | 75         | ((chip adj resistor) and electrodes and (metal adj2 (layer or film)) and (via or hole)) and resin                                      | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/05/16<br>18:47 |
| 40   | BRS                                   | 3 ·        | fringe adj metal and (resin near4 insulating) and electrodes and (semiconductor adj chip) and (metal adj2 (layer or film))             | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM_TDB | 2004/05/16<br>18:59 |
| 41   | BRS                                   | 100        | (resin near4 insulating) same electrodes and (semiconductor adj chip) and (metal adj2 (layer or film)) and (via or hole)               |   | 2004/05/16<br>19:09 |
| 42   | 3RS                                   | 70         | (resin near4 insulating) with electrodes and (semiconductor adj chip) and (metal adj2 (layer or film)) and (via or hole)               |   | 2004/05/16<br>19:09 |
| 43 E | BRS 8                                 | 35         | (resin near4 insulating) with<br>electrodes and substrate and<br>resin same (metal adj2 (layer<br>or film)) and (via or hole)          | PERCHANT, IBM_IDB                                 | 13:13               |
| 44 E | RS 8                                  | 3          | ("5357056" "5508556" "6314637"<br>'6005474").pn.   | USPAT; US-PGPUB;<br>EPO; JPO;<br>DERWENT; IBM TDB | 2004/05/16<br>L9:12 |
| 45 B | RS 1                                  | 3 : 3<br>C | (resin near4 insulating) with electrodes and substrate and sesin same (metal adj2 (layer   | USPAT; US-PGPUB; 2                                | 004/05/16<br>9:19   |
|      | e e e e e e e e e e e e e e e e e e e |            |  |   |                     |
|      |                                       |            |  |   |                     |
|      |                                       |            |  |   |                     |